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What is "Embedded - Microcontrollers"?

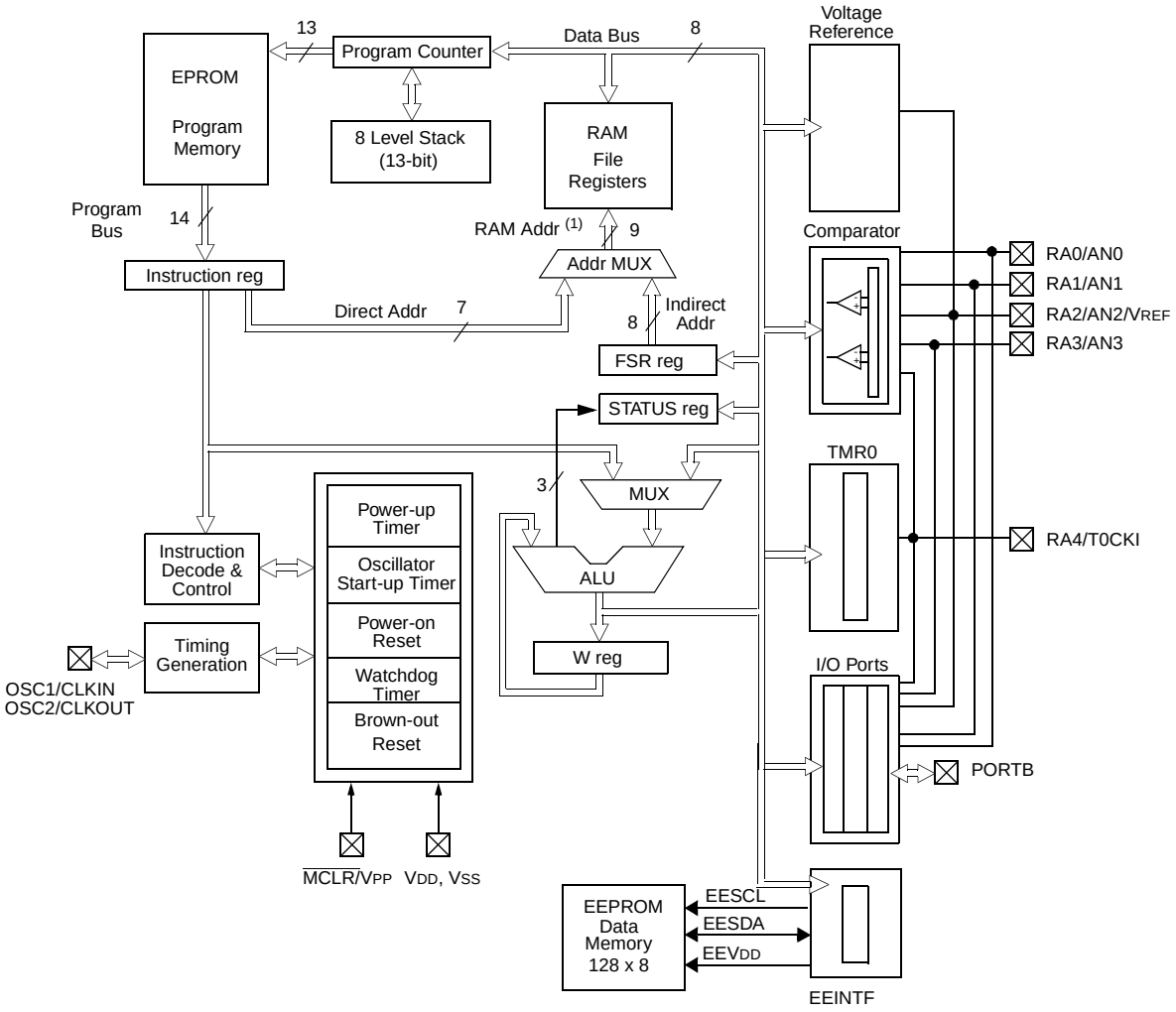
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	13
Program Memory Size	896B (512 x 14)
Program Memory Type	OTP
EEPROM Size	128 x 8
RAM Size	96 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16ce623-04-ss

FIGURE 3-1: BLOCK DIAGRAM

Device	Program Memory	Data Memory (RAM)	EEPROM DATA MEMORY
PIC16CE623	512 x 14	96 x 8	128 x 8
PIC16CE624	1K x 14	96 x 8	128 x 8
PIC16CE625	2K x 14	128 x 8	128 x 8



Note 1: Higher order bits are from the STATUS register.

4.2.2.6 PCON REGISTER

The PCON register contains flag bits to differentiate between a Power-on Reset, an external $\overline{MCLR}$ reset, WDT reset or a Brown-out Reset.

Note: $\overline{BOD}$ is unknown on Power-on Reset. It must then be set by the user and checked on subsequent resets to see if $\overline{BOD}$ is cleared, indicating a brown-out has occurred. The $\overline{BOD}$ status bit is a "don't care" and is not necessarily predictable if the brown-out circuit is disabled (by programming BODEN bit in the configuration word).

REGISTER 4-6: PCON REGISTER (ADDRESS 8Eh)

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
—	—	—	—	—	—	$\overline{POR}$	$\overline{BOD}$
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
-n = Value at POR reset
-x = Unknown at POR reset

bit 7-2: **Unimplemented:** Read as '0'

bit 1: **$\overline{POR}$**: Power-on Reset Status bit
1 = No Power-on Reset occurred
0 = A Power-on Reset occurred (must be set in software after a Power-on Reset occurs)

bit 0: **$\overline{BOD}$**: Brown-out Reset Status bit
1 = No Brown-out Reset occurred
0 = A Brown-out Reset occurred (must be set in software after a Brown-out Reset occurs)

5.2 PORTB and TRISB Registers

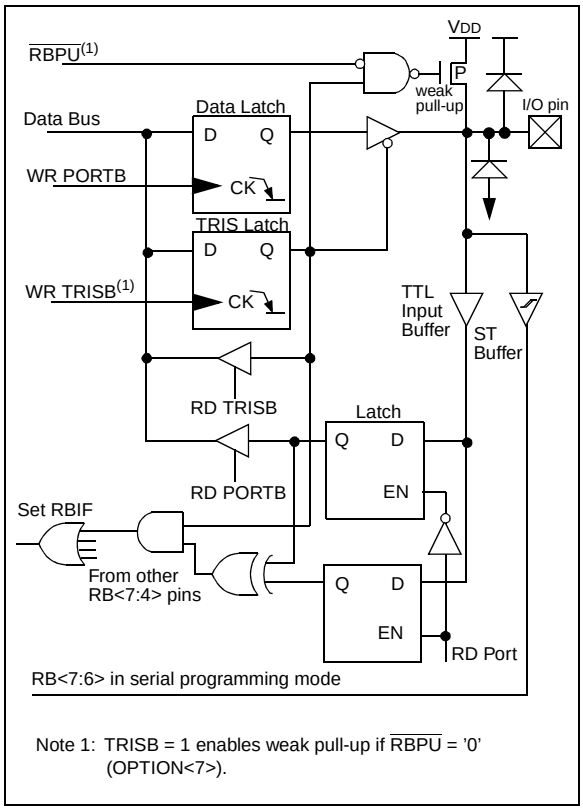
PORTB is an 8-bit wide, bi-directional port. The corresponding data direction register is TRISB. A '1' in the TRISB register puts the corresponding output driver in a high impedance mode. A '0' in the TRISB register puts the contents of the output latch on the selected pin(s).

Reading PORTB register reads the status of the pins, whereas writing to it will write to the port latch. All write operations are read-modify-write operations. So a write to a port implies that the port pins are first read, then this value is modified and written to the port data latch.

Each of the PORTB pins has a weak internal pull-up (|200 PA typical). A single control bit can turn on all the pull-ups. This is done by clearing the $\overline{RBPU}$ (OPTION<7>) bit. The weak pull-up is automatically turned off when the port pin is configured as an output. The pull-ups are disabled on Power-on Reset.

Four of PORTB s pins, RB<7:4>, have an interrupt on change feature. Only pins configured as inputs can cause this interrupt to occur (i.e., any RB<7:4> pin configured as an output is excluded from the interrupt on change comparison). The input pins of RB<7:4> are compared with the old value latched on the last read of PORTB. The mismatch outputs of RB<7:4> are OR ed together to generate the RBIF interrupt (flag latched in INTCON<0>).

FIGURE 5-5: BLOCK DIAGRAM OF RB<7:4> PINS



Note 1: TRISB = 1 enables weak pull-up if $\overline{RBPU}$ = '0' (OPTION<7>).

This interrupt can wake the device from SLEEP. The user, in the interrupt service routine, can clear the interrupt in the following manner:

a) Any read or write of PORTB. This will end the mismatch condition.

b) Clear flag bit RBIF.

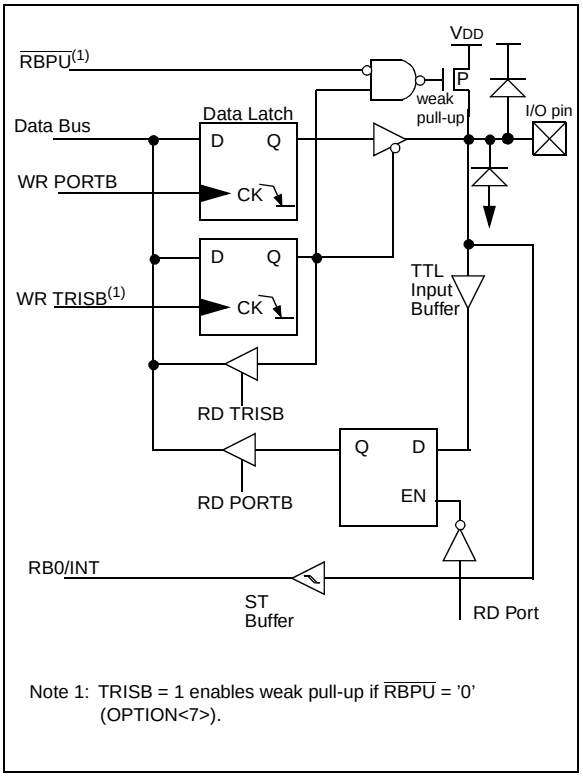
A mismatch condition will continue to set flag bit RBIF. Reading PORTB will end the mismatch condition and allow flag bit RBIF to be cleared.

This interrupt on mismatch feature, together with software configurable pull-ups on these four pins allow easy interface to a key pad and make it possible for wake-up on key-depression. (See AN552, Implementing Wake-Up on Key Strokes .)

Note:	If a change on the I/O pin should occur when the read operation is being executed (start of the Q2 cycle), then the RBIF interrupt flag may not get set.

The interrupt on change feature is recommended for wake-up on key depression operation and operations where PORTB is only used for the interrupt on change feature. Polling of PORTB is not recommended while using the interrupt on change feature.

FIGURE 5-6: BLOCK DIAGRAM OF RB<3:0> PINS



Note 1: TRISB = 1 enables weak pull-up if $\overline{RBPU}$ = '0' (OPTION<7>).

5.3 I/O Programming Considerations

5.3.1 BI-DIRECTIONAL I/O PORTS

Any instruction which writes, operates internally as a read followed by a write operation. The BCF and BSF instructions, for example, read the register into the CPU, execute the bit operation and write the result back to the register. Caution must be used when these instructions are applied to a port with both inputs and outputs defined. For example, a BSF operation on bit5 of PORTB will cause all eight bits of PORTB to be read into the CPU. Then the BSF operation takes place on bit5 and PORTB is written to the output latches. If another bit of PORTB is used as a bidirectional I/O pin (i.e., bit0) and it is defined as an input at this time, the input signal present on the pin itself would be read into the CPU and re-written to the data latch of this particular pin, overwriting the previous content. As long as the pin stays in the input mode, no problem occurs. However, if bit0 is switched into output mode later on, the content of the data latch may now be unknown.

Reading the port register, reads the values of the port pins. Writing to the port register writes the value to the port latch. When using read modify write instructions (i.e., BCF, BSF, etc.) on a port, the value of the port pins is read, the desired operation is done to this value, and this value is then written to the port latch.

Example 5-2 shows the effect of two sequential read-modify-write instructions (i.e., BCF, BSF, etc.) on an I/O port.

A pin actively outputting a Low or High should not be driven from external devices at the same time in order to change the level on this pin (wired-or , wired-and). The resulting high output currents may damage the chip.

EXAMPLE 5-2: READ-MODIFY-WRITE INSTRUCTIONS ON AN I/O PORT

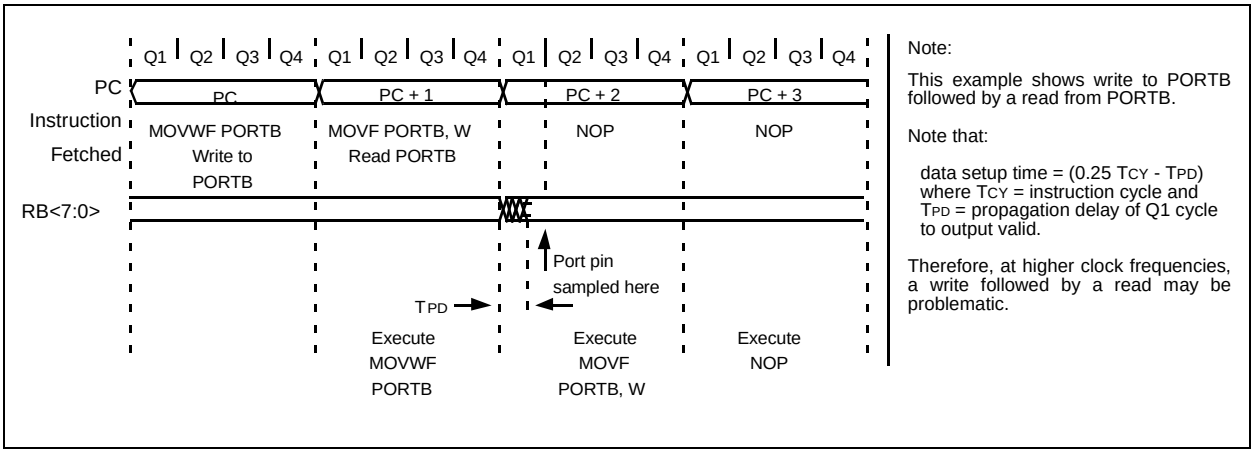
```
; Initial PORT settings:  PORTB<7:4> Inputs
;
;                                PORTB<3:0> Outputs
; PORTB<7:6> have external pull-up and are not
; connected to other circuitry
;
;                                PORT latch   PORT pins
;                                ----------   ----------

      BCF  PORTB, 7          ; 01pp pppp    11pp pppp
      BCF  PORTB, 6          ; 10pp pppp    11pp pppp
      BSF  STATUS,RP0         ;
      BCF  TRISB, 7          ; 10pp pppp    11pp pppp
      BCF  TRISB, 6          ; 10pp pppp    10pp pppp
;
; Note that the user may have expected the pin
; values to be 00pp pppp. The 2nd BCF caused
; RB7 to be latched as the pin value (High).
```

5.3.2 SUCCESSIVE OPERATIONS ON I/O PORTS

The actual write to an I/O port happens at the end of an instruction cycle, whereas for reading, the data must be valid at the beginning of the instruction cycle (Figure 5-7). Therefore, care must be exercised if a write followed by a read operation is carried out on the same I/O port. The sequence of instructions should allow the pin voltage to stabilize (load dependent) before the next instruction causes that file to be read into the CPU. Otherwise, the previous state of that pin may be read into the CPU rather than the new state. When in doubt, it is better to separate these instructions with an NOP or another instruction not accessing this I/O port.

FIGURE 5-7: SUCCESSIVE I/O OPERATION



13.4 Timing Parameter Symbology

The timing parameter symbols have been created with one of the following formats:

1. TppS2ppS
2. TppS

T			
F	Frequency	T	Time

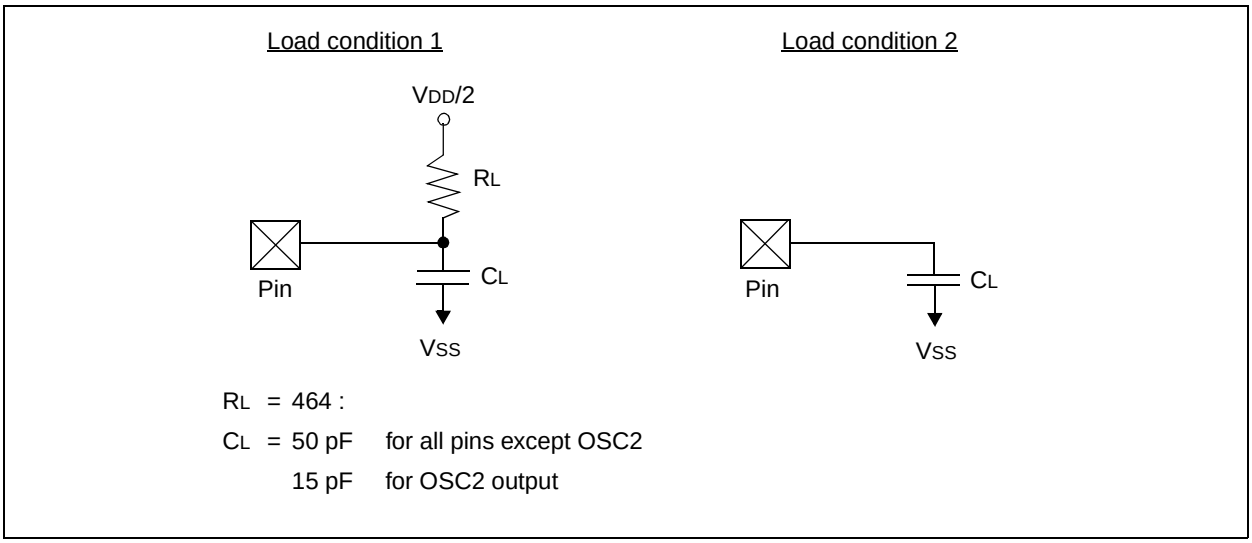
Lowercase subscripts (pp) and their meanings:

pp			
ck	CLKOUT	osc	OSC1
io	I/O port	t0	T0CKI
mc	$\overline{\text{MCLR}}$		

Uppercase letters and their meanings:

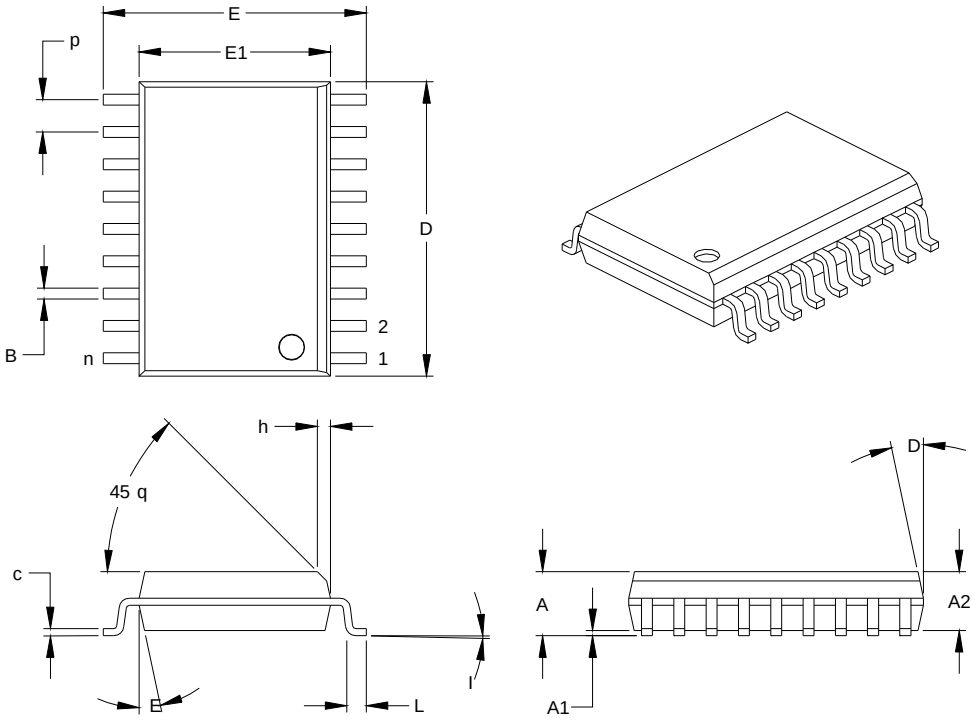
S			
F	Fall	P	Period
H	High	R	Rise
I	Invalid (Hi-impedance)	V	Valid
L	Low	Z	Hi-Impedance

FIGURE 13-4: LOAD CONDITIONS



18-Lead Plastic Small Outline (SO) Wide, 300 mil (SOIC)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.050			1.27	
Overall Height	A	.093	.099	.104	2.36	2.50	2.64
Molded Package Thickness	A2	.088	.091	.094	2.24	2.31	2.39
Standoff	A1	.004	.008	.012	0.10	0.20	0.30
Overall Width	E	.394	.407	.420	10.01	10.34	10.67
Molded Package Width	E1	.291	.295	.299	7.39	7.49	7.59
Overall Length	D	.446	.454	.462	11.33	11.53	11.73
Chamfer Distance	h	.010	.020	.029	0.25	0.50	0.74
Foot Length	L	.016	.033	.050	0.41	0.84	1.27
Foot Angle	l	0	4	8	0	4	8
Lead Thickness	c	.009	.011	.012	0.23	0.27	0.30
Lead Width	B	.014	.017	.020	0.36	0.42	0.51
Mold Draft Angle Top	D	0	12	15	0	12	15
Mold Draft Angle Bottom	E	0	12	15	0	12	15

*Controlling Parameter

Notes:

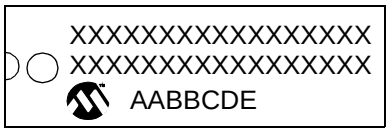
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010 (0.254mm) per side.

JEDEC Equivalent: MS-013

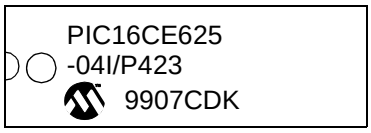
Drawing No. C04-051

14.1 Package Marking Information

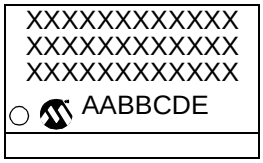
18-Lead PDIP



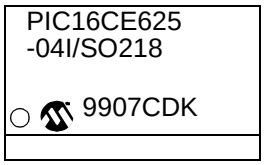
Example



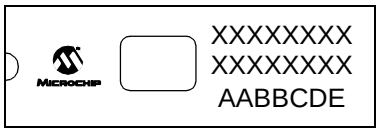
18-Lead SOIC (.300")



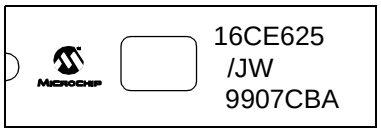
Example



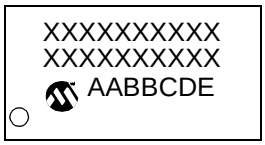
18-Lead CERDIP Windowed



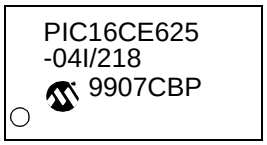
Example



20-Lead SSOP



Example



Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week 01)
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

APPENDIX A: CODE FOR ACCESSING EEPROM DATA MEMORY

Please check our web site at www.microchip.com for code availability.

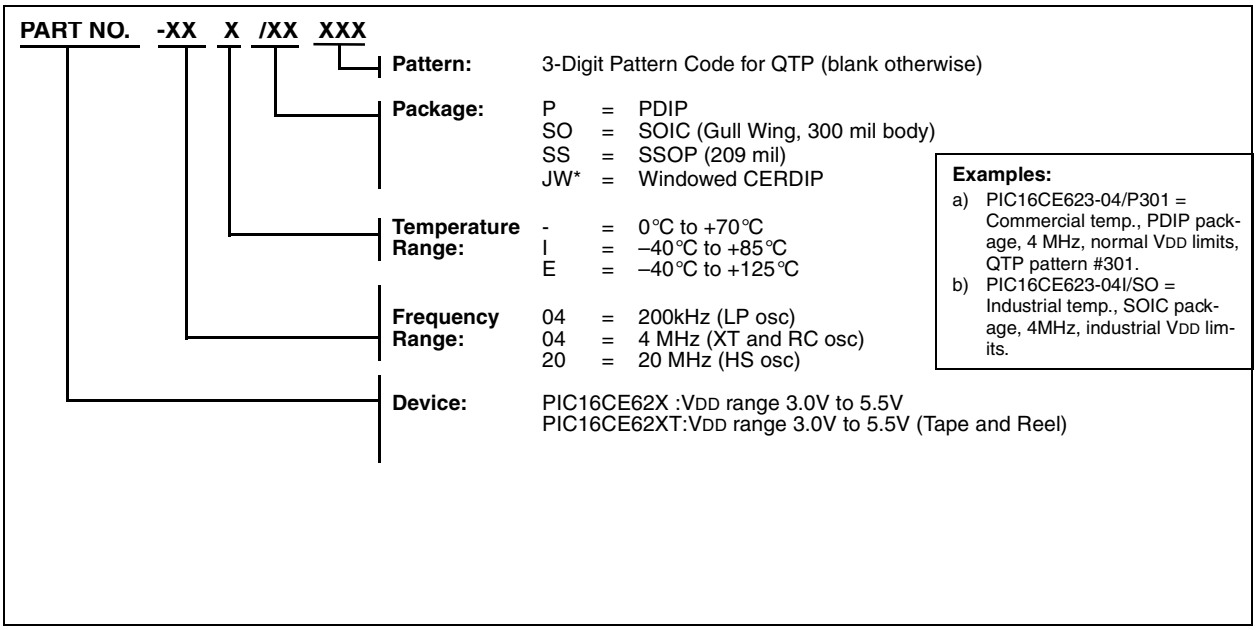
APPENDIX B:REVISION HISTORY

Revision D (January 2013)

Added a note to each package outline drawing.

PIC16CE62X PRODUCT IDENTIFICATION SYSTEM

To order or to obtain information, e.g., on pricing or delivery, please use the listed part numbers, and refer to the factory or the listed sales offices.



* JW Devices are UV erasable and can be programmed to any device configuration. JW Devices meet the electrical requirement of each oscillator type.

Sales and Support

Data Sheets
Products supported by a preliminary Data Sheet may have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

1. Your local Microchip sales office
2. The Microchip Worldwide Site (www.microchip.com)

NOTES: